

## PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT														
NATURE OF CONVEYANCE:	ASSIGNMENT														
CONVEYING PARTY DATA															
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Hang Kyu CHO</td> <td>11/27/2012</td> </tr> <tr> <td>Young Ghyu AHN</td> <td>11/27/2012</td> </tr> <tr> <td>Jae Yeol CHOI</td> <td>11/27/2012</td> </tr> <tr> <td>Doo Young KIM</td> <td>11/27/2012</td> </tr> <tr> <td>Seok Hyun YOON</td> <td>11/27/2012</td> </tr> <tr> <td>Ji Young PARK</td> <td>11/27/2012</td> </tr> </tbody> </table>		Name	Execution Date	Hang Kyu CHO	11/27/2012	Young Ghyu AHN	11/27/2012	Jae Yeol CHOI	11/27/2012	Doo Young KIM	11/27/2012	Seok Hyun YOON	11/27/2012	Ji Young PARK	11/27/2012
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Ji Young PARK	11/27/2012														
RECEIVING PARTY DATA															
Name:	Samsung Electro-Mechanics Co., Ltd														
Street Address:	314 Maetan 3-dong, Yeongtong-gu														
City:	Suwon, Gyunggi-do														
State/Country:	KOREA, REPUBLIC OF														
PROPERTY NUMBERS Total: 1															
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13714104</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13714104										
Property Type	Number														
Application Number:	13714104														
CORRESPONDENCE DATA															
Fax Number:	2027568087														
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>															
Phone:	202-756-8000														
Email:	washington_ip_docket@mwe.com														
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NAME OF SUBMITTER:	Stephen Becker														
Total Attachments: 3 source=DecAssignment_090104-0468#page1.tif source=DecAssignment_090104-0468#page2.tif source=DecAssignment_090104-0468#page3.tif															

CH \$40.00 13714104



ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign to

SAMSUNG ELECTRO-MECHANICS CO., LTD.

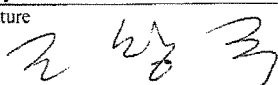
having an address at 314 Maetan 3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea (hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in this document.


I hereby confirm any prior assignment to Assignee, and to the extent that I have not already done so, agree to assign, and hereby do, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by the undersigned had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

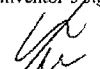
I hereby covenant and agree to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

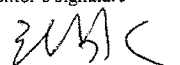
I hereby covenant that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment.


Attorney Docket No. \_\_\_\_\_

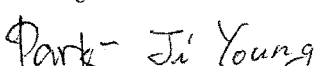
Legal name of first inventor <b>CHO, Hang Kyu</b>	
First inventor's signature 	Date 2012. 11. 27

Legal name of second inventor, if any <b>AHN, Young Ghyu</b>	
Second inventor's signature 	Date 2012. 11. 27

Legal name of third inventor, if any <b>CHOI, Jae Yeol</b>	
Third inventor's signature 	Date 2012. 11. 27

Legal name of fourth inventor, if any <b>KIM, Doo Young</b>	
Fourth inventor's signature 	Date 2012. 11. 27

Legal name of fifth inventor, if any <b>YOON, Seok Hyun</b>	
Fifth inventor's signature 	Date 2012. 11. 27

Legal name of sixth inventor, if any <b>PARK, Ji Young</b>	
Sixth inventor's signature 	Date 2012. 11. 27